one detection tilt angle Sd with one substrate 110 and stores it in the memory 40.

[0034]

If the detection tilt angle Sd is obtained, the controller 20 checks the presence or absence of a next substrate 110 (S16). If there is no next substrate 110 (No in S16), the manufacturing process ends. On the other hand, in a case in which there is a next substrate 110 (Yes in S16), the controller 20 determines whether or not the holding surface tilt angle Sb needs to be corrected for the next substrate 110 on the basis of the detection tilt angle Sd (S18). Specifically, the controller 20 compares the obtained detection tilt angle Sd with a specified allowable tilt value. As a result of the comparison, in a case in which the detection tilt angle Sd is equal to or less than the allowable tilt value, it is determined that the current holding surface tilt angle Sb is appropriate and correction is not necessary (No in S18). In this case, the controller 20 returns to step S20 and executes the next bonding process on the new substrate 110 without correcting the holding surface tilt angle Sb. On the other hand, when the detection tilt angle Sd exceeds the allowable tilt value, the controller 20 determines that the holding surface tilt angle Sb needs to be corrected (Yes in S18). In this case, the controller 20 reduces a next detection tilt angle Sd and calculates a correction amount C such that the tilt angle of the chip 100 approaches the tilt angle of the installing surface 112 (S20). The calculation of the correction amount C will be described later.

[0035]

If the correction amount C can be calculated, the controller 20 corrects the holding surface tilt angle Sb by the correction amount C using the holding surface adjusting mechanism 18 (S22). Specifically, the amount of the advancing and retreating of the support column 36 is adjusted to change the tilt angle of the tilt plate 34 to a tilt angle according to the correction amount C. Then, the installing tool 22 switched to the free state is pressed against the tilt plate 34 to make the chip holding surface 26 conform the tilt plate 34, and then the installing tool 22 is switched to the fixed state. When the correction of the holding surface adjusting mechanism 18